



## Material Content Data Sheet



<b>Sales Product Name</b>		BSZ042N04NS G		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA001579676						
<b>Package</b>		PG-TSDSON-8-2		<b>Weight*</b>		40.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.836	4.57	4.57	45675	45675
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		52	
	non noble metal	zinc	7440-66-6	0.008	0.02		209	
	non noble metal	iron	7439-89-6	0.168	0.42		4170	
wire	non noble metal	copper	7440-50-8	6.808	16.93	17.38	169326	173757
	non noble metal	copper	7440-50-8	0.036	0.09	0.09	906	906
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.09		909
	plastics	epoxy resin	-	1.882	4.68		46817	
	inorganic material	silicondioxide	60676-86-0	16.356	40.70	45.47	406811	454537
leadfinish	non noble metal	tin	7440-31-5	0.387	0.96	0.96	9629	9629
plating	noble metal	silver	7440-22-4	0.963	2.39	2.39	23942	23942
solder	non noble metal	tin	7440-31-5	0.037	0.09		916	
	noble metal	silver	7440-22-4	0.046	0.11		1145	
	non noble metal	lead	7439-92-1	1.759	4.37	4.57	43742	45803
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		107	
	non noble metal	iron	7439-89-6	0.086	0.21		2145	
	non noble metal	copper	7440-50-8	3.501	8.71	8.93	87084	89363
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		47	
	non noble metal	zinc	7440-66-6	0.008	0.02		188	
	non noble metal	iron	7439-89-6	0.151	0.38		3753	
	non noble metal	copper	7440-50-8	6.127	15.24	15.64	152400	156388
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com